

[54] SHEET-METAL HEAT SINK FOR
ELECTRONIC SEMICONDUCTOR DEVICES

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[**] Term: 14 Years

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[52] U.S. Cl. D13/23
[58] Field of Search D13/23; 174/16 HS;
357/81; 165/80, 80 A, 80 B

[56] References Cited
U.S. PATENT DOCUMENTS

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Attorney, Agent, or Firm—James E. Mrose

[57] CLAIM

The ornamental design for a sheet-metal heat sink for
electronic semiconductor devices, substantially as
shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a sheet-metal heat sink
for electronic semiconductor devices showing my new
design; the broken lines being shown for illustrative
purposes, only;
FIG. 2 is a front elevational view of the same heat sink;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a side elevational view thereof, looking
toward the right side of the heat sink as it is shown in
FIG. 1;
FIG. 5 is a side elevational view thereof, looking
toward the left side of the heat sink as it is shown in
FIG. 1;
FIG. 6 is a top plan view thereof; and
FIG. 7 is a bottom plan view thereof.

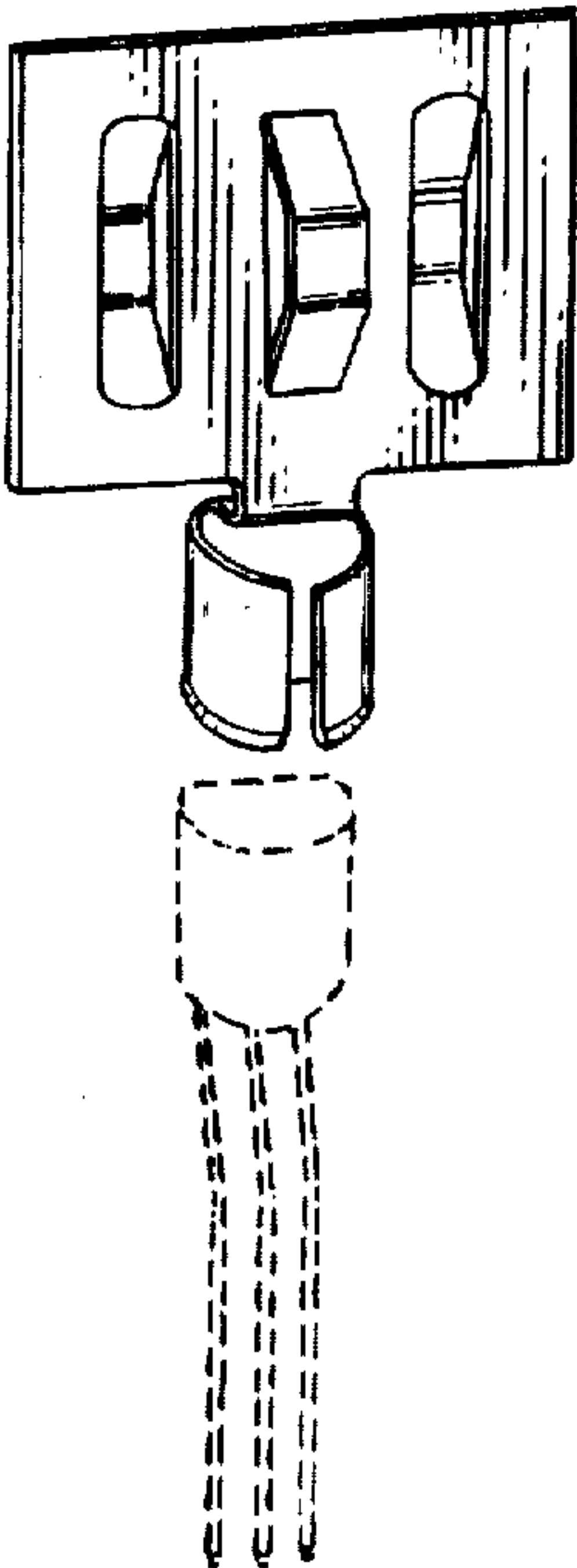


FIG. 1

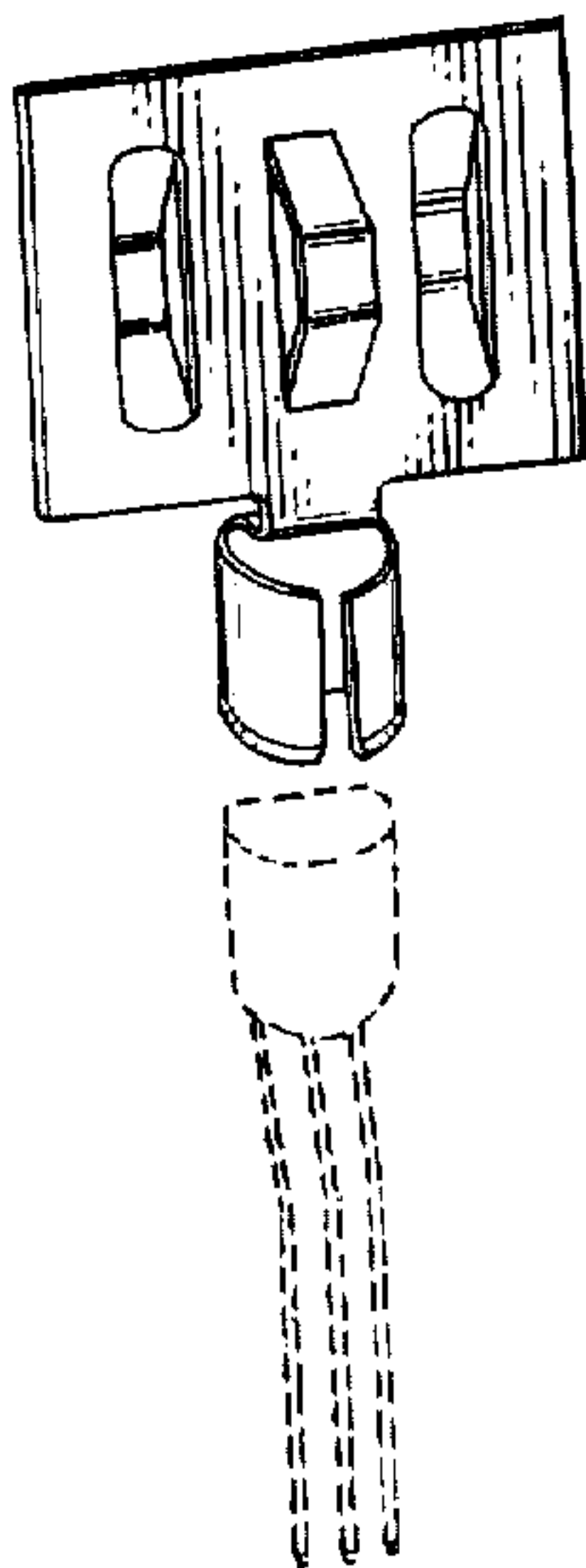


FIG. 2

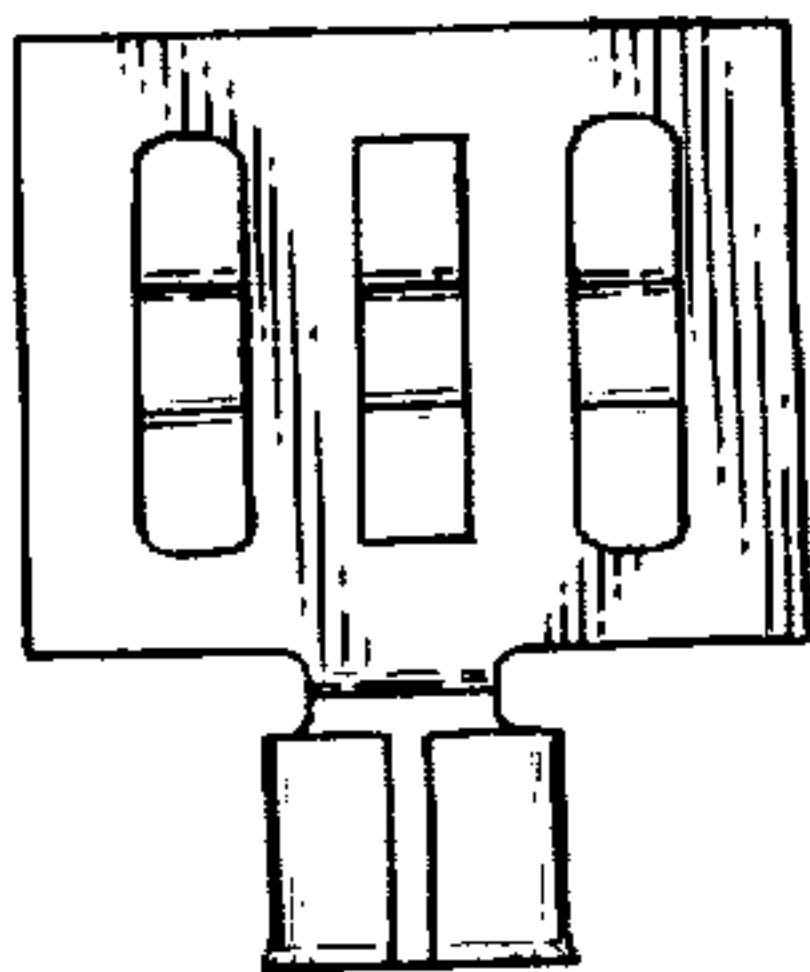


FIG. 3

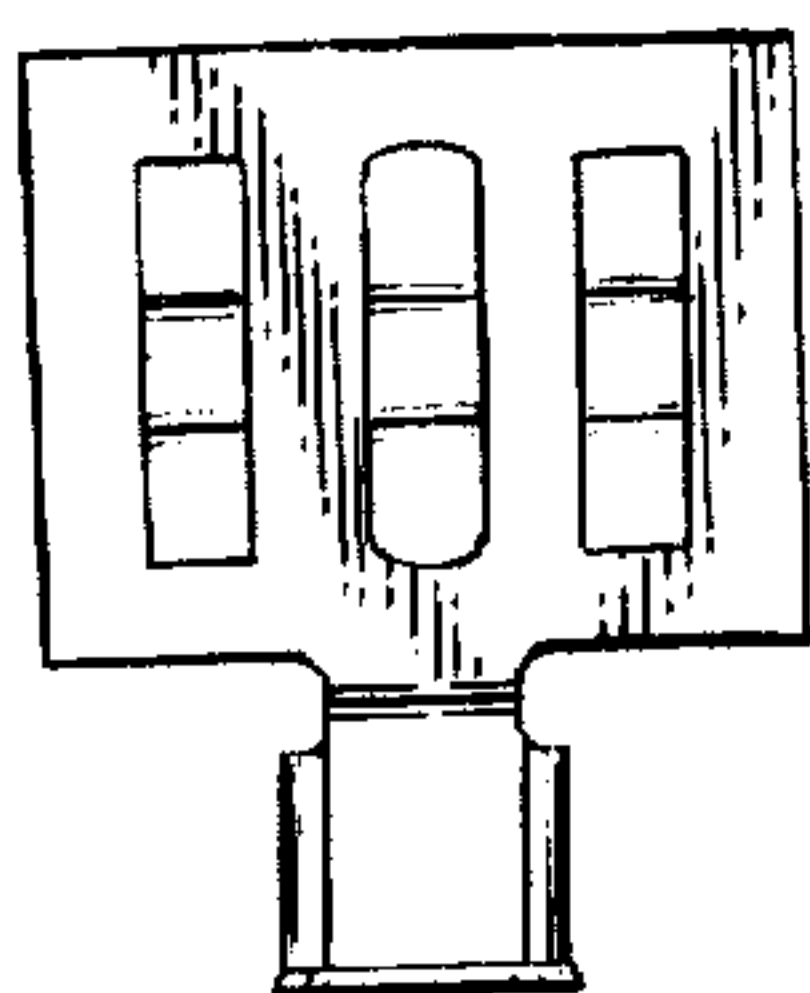


FIG. 4

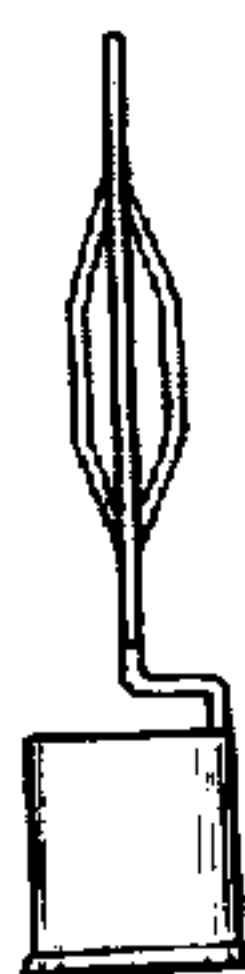


FIG. 5



FIG. 6



FIG. 7

